

General Features

- Excellent gate charge x $R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 150°C operating temperature
- Pb-free lead plating

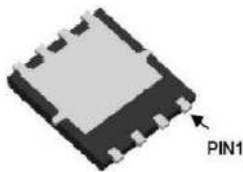
Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

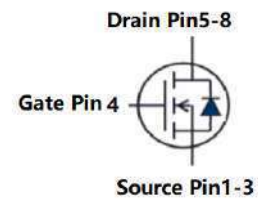
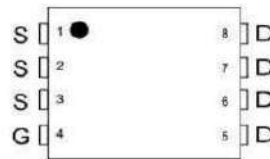
Product Summary



V_{DS}	120	V
$R_{DS(on),Typ} @ V_{GS}=10V$	5.5	mΩ
I_D	90	A



DFN5*6-8



N-Channel

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	120	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	90	A
Drain Current-Continuous($T_C=100^\circ\text{C}$)	$I_D(100^\circ\text{C})$	64	A
Pulsed Drain Current	I_{DM}	360	A
Maximum Power Dissipation	P_D	130	W
Derating factor		1.04	W/°C
Single pulse avalanche energy ^(Note 4)	E_{AS}	400	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.92	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	°C/W

**Electrical Characteristics (T_C=25°C unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	120		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =96V, V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.2	1.7	2.5	V
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =45A	-	5.5	6.5	mΩ
		V _{GS} =4.5V, I _D =45A		6.6	7.8	
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =50A		60	-	S
Dynamic Characteristics (Note 3)						
Input Capacitance	C _{iss}	V _{DS} =60V, V _{GS} =0V, F=1.0MHz	-	4240	-	pF
Output Capacitance	C _{oss}		-	260	-	pF
Reverse Transfer Capacitance	C _{rss}		-	29	-	pF
Switching Characteristics (Note 3)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =60V, I _D =45A V _{GS} =10V, R _G =1.6Ω	-	20	-	nS
Turn-on Rise Time	t _r		-	15	-	nS
Turn-Off Delay Time	t _{d(off)}		-	40	-	nS
Turn-Off Fall Time	t _f		-	10	-	nS
Total Gate Charge	Q _g	V _{DS} =60V, I _D =45A, V _{GS} =10V	-	90	-	nC
Gate-Source Charge	Q _{gs}		-	21	-	nC
Gate-Drain Charge	Q _{gd}		-	23.5	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 2)	V _{SD}	V _{GS} =0V, I _S =45A	-	-	1.2	V
Diode Forward Current	I _S		-	-	90	A
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = 45A di/dt = 100A/μs (Note 3)	-	70	-	nS
Reverse Recovery Charge	Q _{rr}		-	137	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
3. Guaranteed by design, not subject to production
4. EAS condition : T_J=25°C, V_{DD}=50V, V_G=10V, L=0.5mH, R_G=25Ω



Typical Electrical and Thermal Characteristics

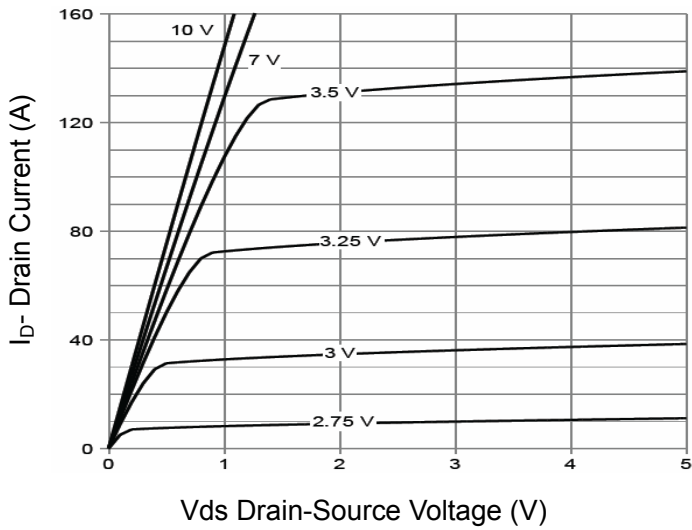


Figure 1 Output Characteristics

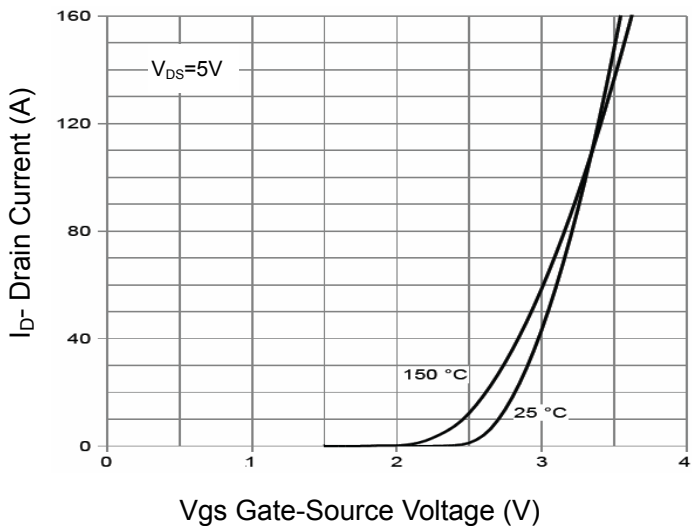


Figure 2 Transfer Characteristics

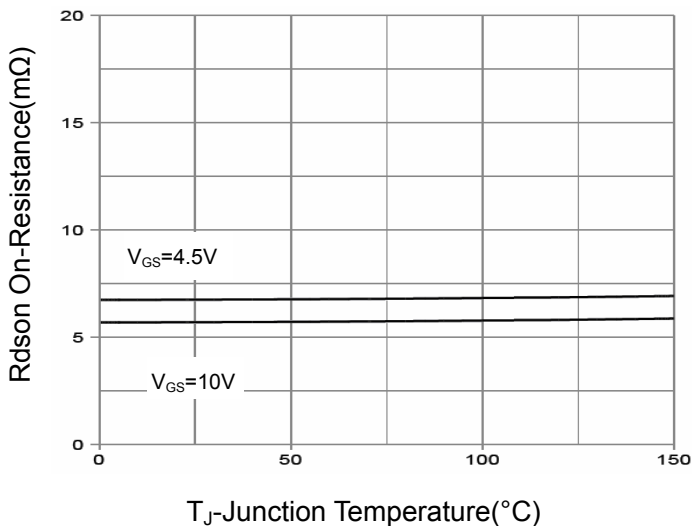


Figure 3 Rdson-Junction Temperature

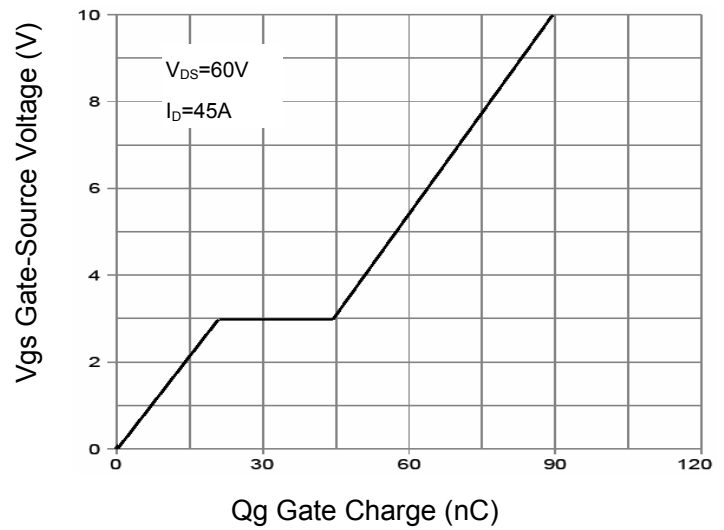


Figure 4 Gate Charge

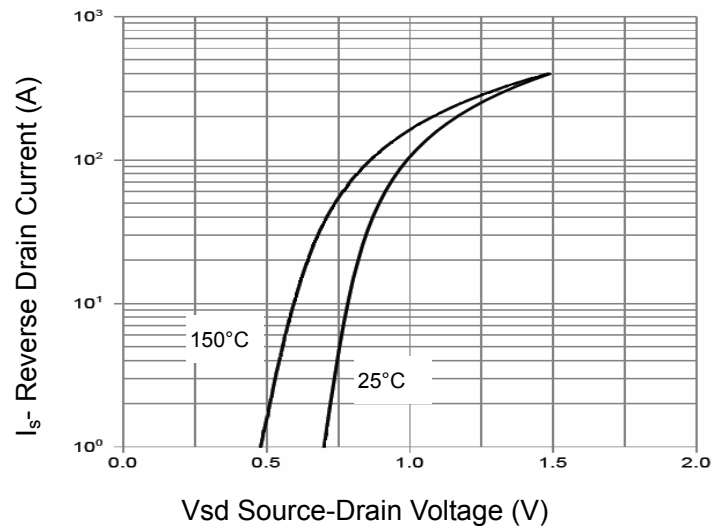


Figure 5 Source-Drain Diode Forward

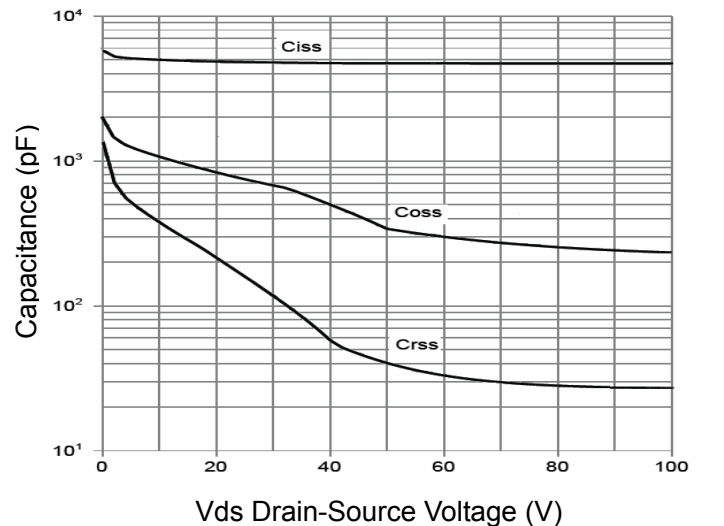
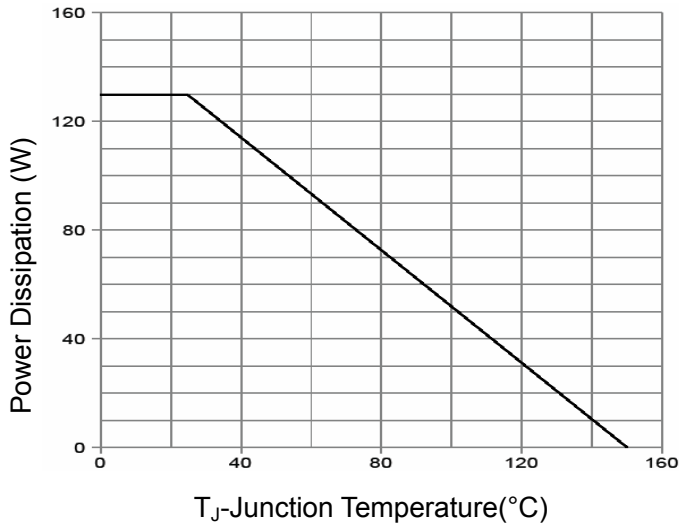
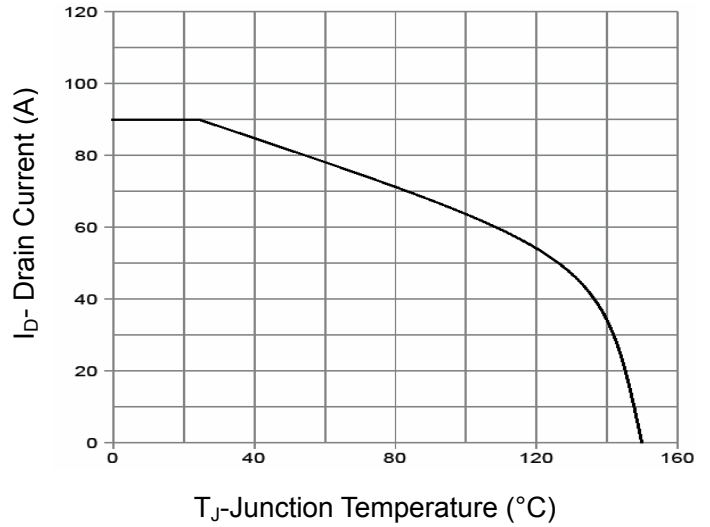


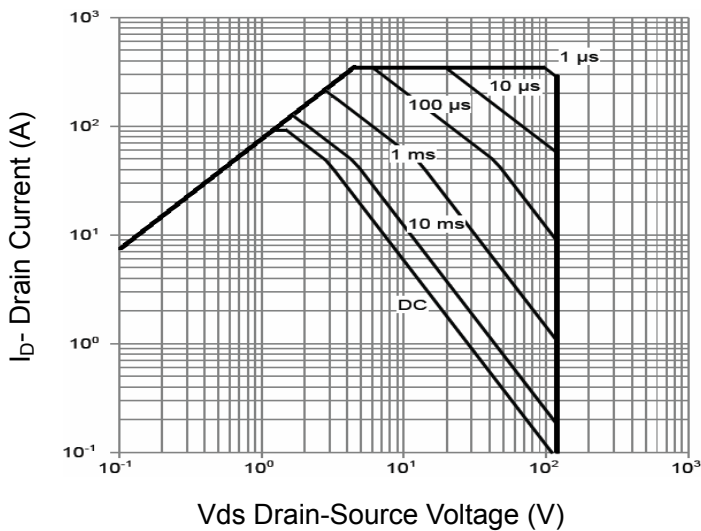
Figure 6 Capacitance vs Vds



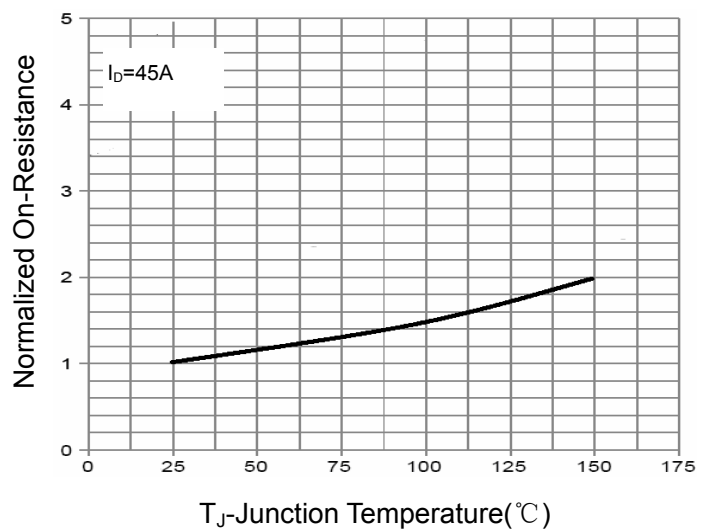
T_J-Junction Temperature(°C)
Figure 7 Power De-rating



T_J-Junction Temperature (°C)
Figure 9 Current De-rating



V_{ds} Drain-Source Voltage (V)
Figure 8 Safe Operation Area



T_J-Junction Temperature(°C)
Figure 10 R_{ds(on)}-Junction Temperature

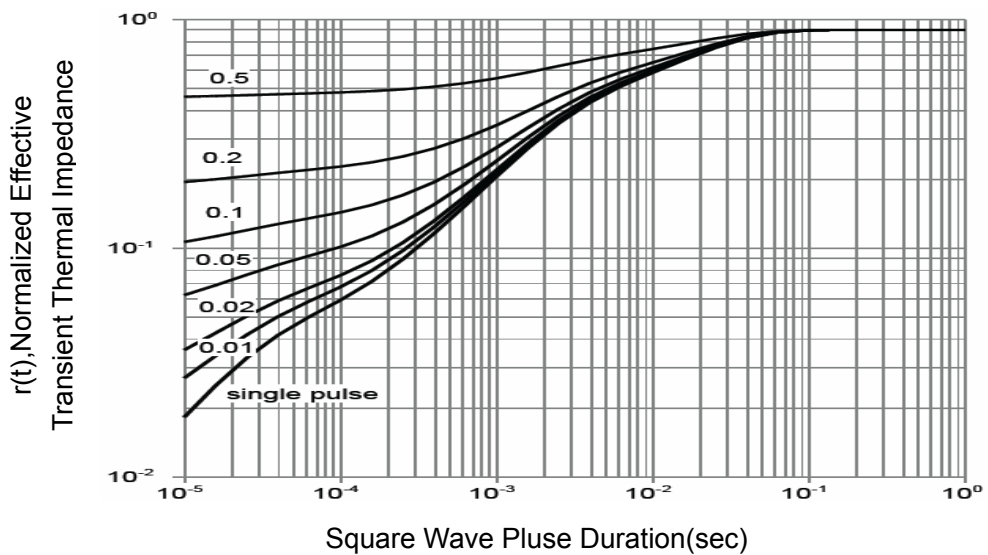
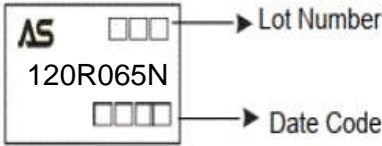


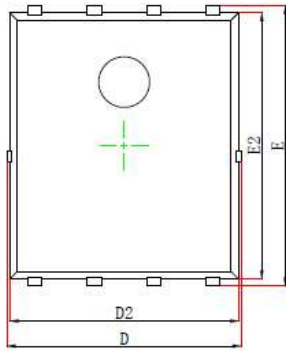
Figure 11 Normalized Maximum Transient Thermal Impedance

Ordering and Marking Information

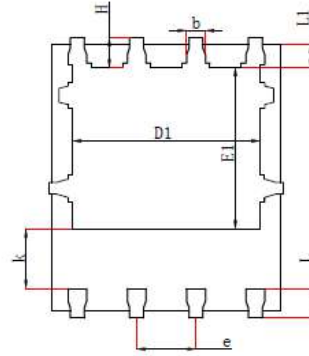
Ordering Device No.	Marking	Package	Packing	Quantity
ASDM120R065NQ-R	120R065N	DFN5*6-8	Tape&Reel	4000/Reel

PACKAGE	MARKING
DFN5*6-8	 <p>The marking diagram shows a rectangular package with the following markings: 'AS' logo in the top left, '120R065N' in the center, and two sets of four small squares. The top set of squares is labeled 'Lot Number' and the bottom set is labeled 'Date Code'.</p>

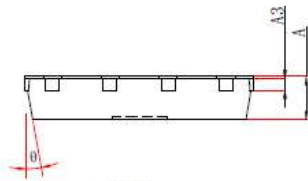
DFN5x6_P, 8 Leads



Top View
[顶视图]



Bottom View
[背视图]



Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°

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